

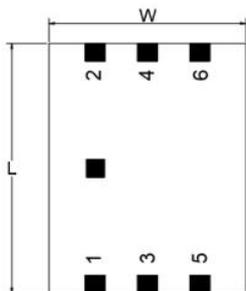
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

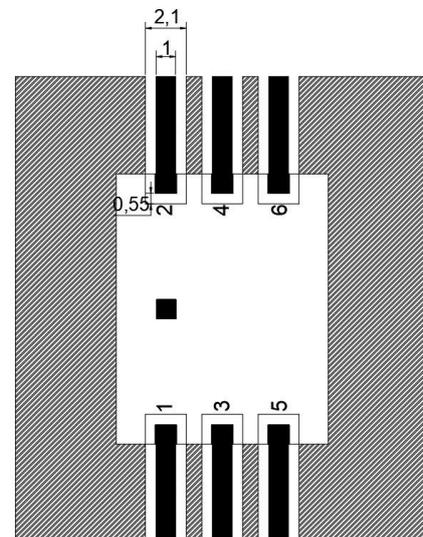
NO.	Specification			
		LPF1	LPF2	LPF3
1	Frequency range (MHz)	30~43	43~62	62~88
2	Insertion Loss (dB) @25°C	≤1.45	≤1.45	≤1.4
3	VSWR (In BW)	≤1.5	≤1.5	≤1.5
4	Ripple	≤1.0	≤1.0	≤1.0
5	Impedance (Ω)	50	50	50
6	Attenuation (dB)	60~352MHz	≥42	-
		86~352 MHz	-	≥45
		124~352 MHz	-	-
7	Power(W)	6W		
Operating & Storage Condition (Component)				
Operation Temperature Range: -40°C ~ +85°C				
Storage Temperature Range: -40°C ~ +85°C				
Storage Condition before Soldering (Included packaging material)				
Storage Temperature Range: +5 ~ +40 °C				
Humidity: 30 to 70% relative humidity				

Construction

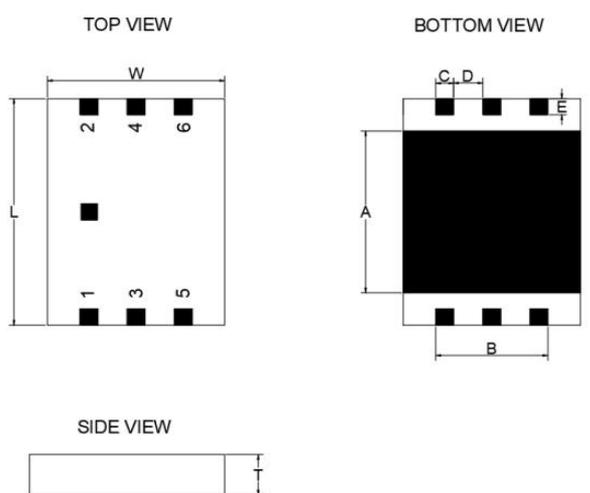


PIN	Connection	PIN	Connection
1	LPF1 input Port	2	LPF1 output Port
3	LPF2 input Port	4	LPF2 output Port

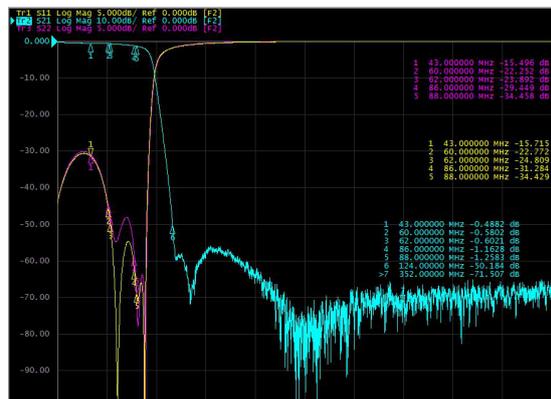
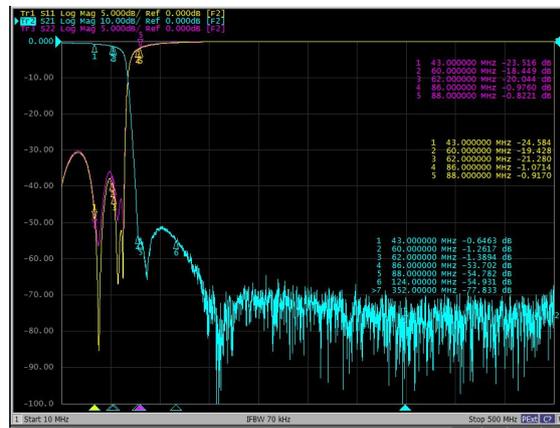
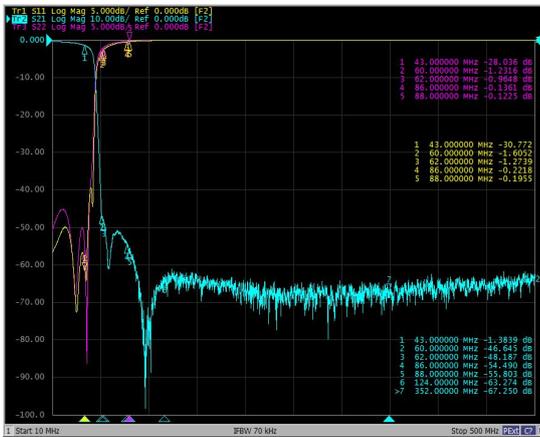
Mounting Considerations



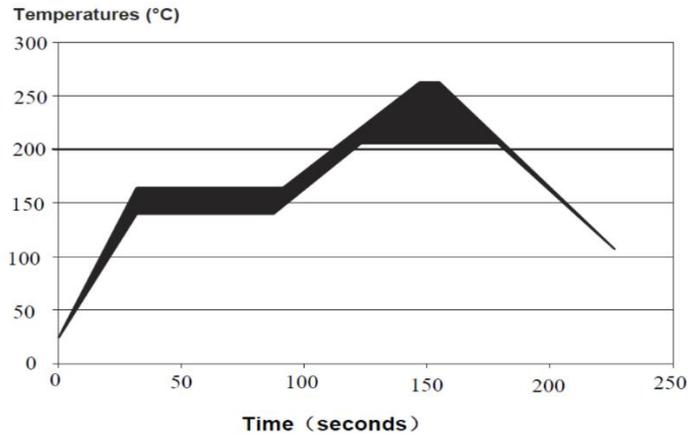
Dimensions

Figure	Symbol	Dimension (mm)
	L	14.00 ± 0.30
	W	10.90 ± 0.30
	T	2.50 ± 0.20
	A	10.00 ± 0.20
	B	6.90 ± 0.20
	C	1.10 ± 0.15
	D	1.80 ± 0.15
E	1.00 ± 0.15	

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.